



PATENT

Attorney Docket No. ME-31607

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of : Teck Kheng Lee  
Serial No. : 10/050,507  
Filing Date : January 16, 2002  
For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking  
Group Art Unit : 2812  
Confirmation No. : 7687

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**CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10**

I hereby certify that, on the date shown below, this correspondence is being:

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**37 CFR 1.8(a)**

**37 CFR 1.10**

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Date: Jan 6, 2003

*[Signature]*

Assistant Commissioner for Patents  
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**PRELIMINARY AMENDMENT**

Sir:

Prior to substantive examination, Applicant requests the following amendments be made in the application.

**IN THE CLAIMS**

Please amend the claims as shown in the attached replacement sheets submitted under 37 C.F.R. § 1.121(c). A blacklined version is enclosed to illustrate the amendments to the claims.

01/06/2003 NNDHARRH1 00000075 10050507

01 FC:1202 558.00 OP  
02 FC:1201 504.00 OP

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